

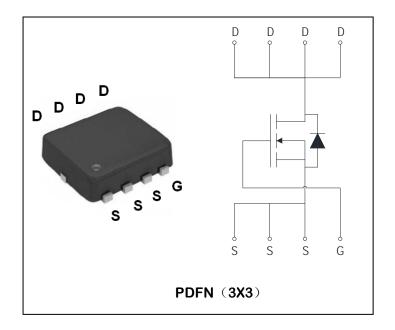
N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	$R_{DS(ON)}$ (m Ω)
30V	80A	3.3 m Ω

Features:

- Low Gate Charge for Fast Switching Application
- Low Rds(ON) to Minimize Conductive Loss
- 100% EAS Guaranteed
- Optimized V(BR)DSS Ruggedness
- Green Device Available



Description:

The ADM80N03Z uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Absolute Maximum Ratings (TA = 25°C unless otherwise specifed)

Symbol	Parameter	Ratings	Unit		
Common F	Common Ratings				
V _{DSS}	Drain-Source Voltage		30		
V _{GSS}	Gate-Source Voltage		±20	V	
TJ	Maximum Junction Temperature		150	°C	
T _{STG}	Storage Temperature Range		-55 to150	°C	
ls	Diode Continuous Forward Current T _C =25°C		80	Α	
Mounted o	n Large Heat Sink				
Ідм	300µs Pulse Drain Current Tested (2)	T _C =25°C, V _{GS} =10V	320	Α	
lσ	Continuous Drain Current (1)	T _C =25°C, V _{GS} =10V	80	Α	
		T _C =100°C V _{GS} =10V	52	Α	
Po	Maximum Power Dissipation	T _C =25°C	31.7	W	

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
RthJC	Thermal resistance junction-case max (1)	3.94	°C/W
RthJA	Thermal resistance junction-ambient max (1)	30	°C/W



ADM80N03Z

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
On/off Charac	eteristics					
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	30			V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} =0V T _J =25°C			1.0	uA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.0	1.6	2.5	V
Igss	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
Process	D :: 0 0 111 D :: 1 (0)	V _{GS} = 10V, I _{DS} =30A		2.5	3.3	mΩ
Rds(on)	Drain-SourceOn-stateResistance(2)	V _{GS} = 4.5V, I _{DS} =20A		4.5	6.5	
Dynamic Chara	acteristics					
Ciss	Input Capacitance	V _{GS} =0V,		3500		
Coss	Output Capacitance	V _{DS} = 15V,		500		pF
Crss	Reverse Transfer Capacitance	Frequency=1.0MHz		431		
Switching Char	racteristics					•
td(ON)	Turn-on Delay Time(1)	V _{DD} =20V,		26		
tr	Turn-on Rise Time(1)	I _D = 30A, V _{GS} = 10V,		24		
td(OFF)	Turn-off Delay Time(1)	R _{GEN} =3 Ω		91		ns
tf	Turn-off Fall Time(1)			39		
Qg	Total Gate Charge(1)	V _{DS} =15V, V _{GS} = 10V,		38		
Qgs	Gate-Source Charge(1)	I _{DS} =30A		9		nC
Qgd	Gate-Drain Charge(1)			13		
Avalanche Cha	aracteristics					
		V _{DD} =24V,L=0.5mH ,V _{GS} =10				
EAS	Single Pulse Avalanche Energy (3)	$V,R_g=25\Omega$, IAS=30A	225		mJ	
		T _J =25°C				
Diode Charact	eristics					
Vsp	Diode Forward Voltage(2)	I _{SD} = 30A, V _{GS} = 0 ,T _J =25°C			1.2	V
trr	Reverse Recovery Time	1 -30 \ \d\ \d\ \d\ \d\ \-400 \\ \d\ \		42		ns
q rr	Reverse Recovery Charge	- I _{SD} =20A, dI _{SD} /dt=100A/μs		39		nC

NOTES:

- 1. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,\,300\text{us}$, duty cycle $\,\leq\,\,2\%$
- 3.The Min. value is 100% EAS tested guarantee.



Typical Performance Characteristics

Figure1: Output Characteristics

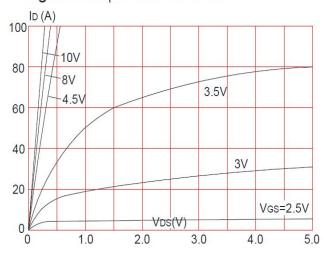


Figure 3:On-resistance vs. Drain Current

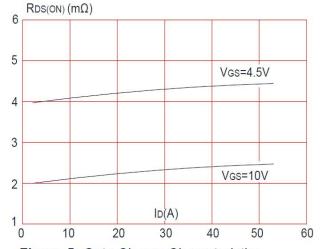


Figure 5: Gate Charge Characteristics

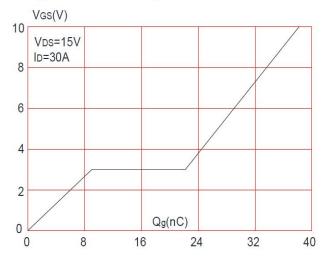


Figure 2: Typical Transfer Characteristics

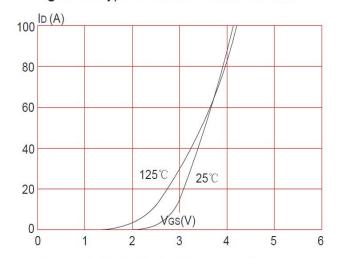


Figure 4: Body Diode Characteristics

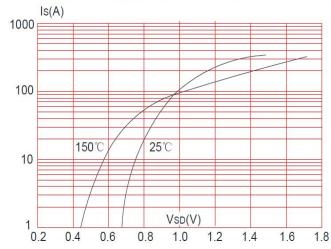


Figure 6: Capacitance Characteristics

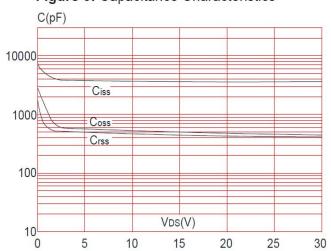




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

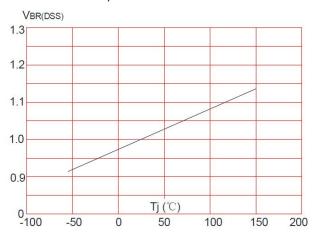


Figure 9: Maximum Safe Operating Area

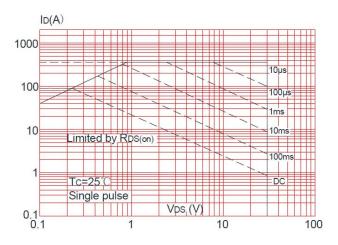


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

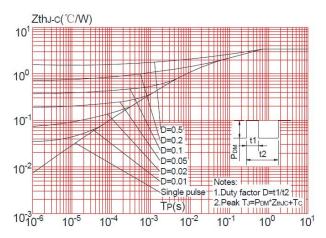


Figure 8: Normalized on Resistance vs. Junction Temperature

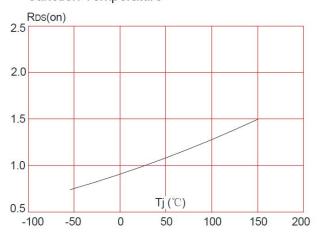


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

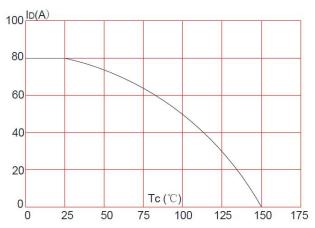




Figure 12: Switching Time Waveform

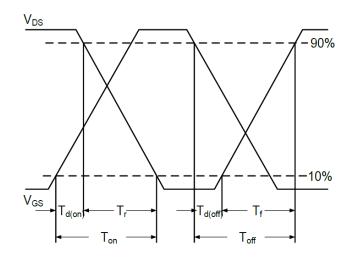
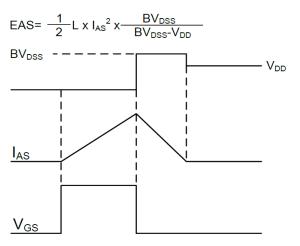
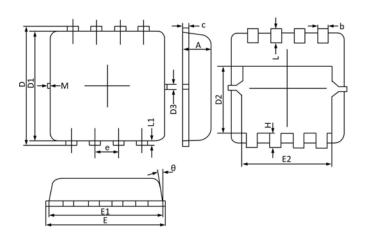


Figure 13: EAS Waveform



PDFN (3X3) Package Dimension



Correcte	Dimensions In		Dimensions In		
Symb ol	Millimeters		Inches		
Oi	Min.	Max.	Min.	Max.	
Α	0.700	0.800	0.028	0.031	
b	0.250	0.350	0.010	0.013	
С	0.100	0.250	0.004	0.009	
D	3.250	3.450	0.128	0.135	
D1	3.000	3.200	0.119	0.125	
D2	1.780	1.980	0.070	0.077	
D3	0.130	REF	0.005REF		
Е	3.200	3.400	0.126	0.133	
E1	3.000	3.200	0.119	0.125	
E2	2.390	2.590	0.094	0.102	
Н	0.300	0.500	0.011	0.019	
М	0.150REF		0.006REF		
е	0.650 TYP.		0.026 TYP.		
L	0.300	0.500	0.011	0.019	
L1	0.130REF		0.005REF		
θ	0°	12°	0°	12°	

Ordering information

Part number	Package	Marking	Packing	Quantity
ADM80N03Z	PDFN3*3	M80N03Z	Embossed tape	5000pcs





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